WHAT IS CLAIMED IS:

1. A transfer body including at least a peelable layer, a transparent conductive layer and an adhesive layer all sequentially laminated on a supporting body, wherein said supporting body has a heat resisting property enough to withstand heat treatment to said layers on said supporting body and a large rigidity compared with an opponent member to which said layers are to be transferred, and wherein said peelable layer is formed to have a pull strength of 100 g/cm or more.

2. A transfer body according to claim 1, wherein said transparent conductive layer is in the form of a pattern.

3. A transfer body according to claim 1, wherein an intermediate layer is disposed between said transparent conductive layer and said adhesive layer.

4. A transfer body according to claim 3, wherein a color filter is formed between said transparent conductive layer and said intermediate layer, or between said intermediate layer and said adhesive layer.

5. A transfer body according to claim 1, wherein said peelable layer is a polyimide resin having a thickness of 1.3 μm or more and preferably 2μm or more.

6. A transfer body according to claim 4, wherein a barrier layer composed of inorganic material is disposed between said peelable layer and

said transparent conductive layer and/or between said transparent conductive layer and said color filter layer.

7. A method for reproducing a transfer body, wherein said transfer body includes a peelable layer, a transparent conductive layer and an adhesive layer all sequentially laminated on a supporting body and wherein said transfer body further includes a color filter layer disposed between said peelable layer and said adhesive layer and a barrier layer disposed between said color filter layer and said peelable layer,

said method comprising the steps of removing said color filter layer from said supporting body by using said barrier layer as an etching stopper by a plasma etching method in which oxygen is chiefly used or by a reactive ion etching method (RIE); and

then sequentially forming at least a color filter layer and an adhesive layer on said supporting body, thereby reproducing said transfer body.

8. A method for forming a transparent conductive layer using a transfer body comprising the steps of:

forming a transfer body by sequentially laminating at least a peelable layer, a transparent conductive layer and an adhesive layer on a supporting body having a heat resisting property enough to withstand heat treatment to said layers on said supporting body and a large rigidity compared with an opponent member to which said layers are to be transferred;

adhesively sticking said transfer body to one surface of a film composed of plastic material through said adhesive layer; and peeling off said transfer body inclusive said peelable layer from said supporting body through said peelable layer, thereby transferring said transparent conductive layer to said film composed of plastic material;

wherein said peelable layer has a pull strength of 100 g/cm or more.

9. A method for forming a transparent conductive layer using a transfer body according to claim 8, wherein said transparent conductive layer is in the form of a pattern.

10. A method for forming a transparent conductive layer using a transfer body according to claim 8, wherein an intermediate layer is disposed between said transparent conductive layer and said adhesive layer.

11. A method for forming a transparent conductive layer using a transfer body according to claim 10, wherein a color filter is formed between said transparent conductive layer and said intermediate layer, or between said intermediate layer and said adhesive layer.

12. A method for forming a transparent conductive layer using a transfer body according to one of claims 8 to 11, wherein one end portion of said film composed of plastic material is temporality fixed to a roll having a diameter of 50 mm or more and preferably 100 mm or more and thereafter said roll is substantially rollingly moved to peel off said transfer body inclusive said peelable layer from said supporting body through said

peelable layer, thereby transferring said transparent conductive layer to the one surface of said film composed of plastic material.

13. A method for forming a transparent conductive layer using a transfer body according to one of claims 8 to 11, wherein a barrier layer composed of inorganic material is disposed between said peelable layer and said transparent conductive layer and/or between said transparent conductive layer and said color filter layer.

14. A method for forming a transparent conductive layer using a transfer body according to claim 13, wherein said transparent conductive layer is transferred to the one surface of said film composed of plastic material and thereafter removing said peelable layer by a plasma etching method or reactive ion etching method (RIE) in which oxygen is chiefly used.

15. A method for forming a transparent conductive layer using a transfer body according to claim 8, wherein said peelable layer is a polyimide resin having a thickness of 1.3 μm or more and preferably 2μm or more.

16. A method for forming a transparent conductive layer using a transfer body according to claim 8 to 11, wherein said peelable layer is composed of a colored resin, thereby enabling to recognize a terminal point at the time of removal of said peelable layer.